

MATERIALS AND FINISHES:

BODY BERYLLIUM COPPER
PLATED GOLD

CONTACT BERYLLIUM COPPER
PLATED GOLD

INSULATOR TEFLON

SMP JACK
INTERFACE

PLATING MEASUREMENT
ZONE. SEE NOTE 2.
FOR 73415-3358

PLATING THICKNESS
MEASUREMENT ZONE.
INSIDE DIAMETER .
SEE NOTE 1. FOR 73415-3358

NOTE 1: FOR 73415-3358
GOLD PLATING THICKNESS MUST
BE 10 MICROINCHES MINIMUM AT
STATED LOCATION.

NOTE 2: FOR 73415-3358
GOLD PLATING THICKNESS MUST
BE 30 MICROINCHES MINIMUM AT
STATED LOCATION.

73415-3356	PLACE 73415-3351 INTO SMALL TRAY
73415-3355	PLACE 73415-3350 INTO SMALL TRAY
PART NO.	DESCRIPTION

PS-89675-3320	PRODUCT SPECIFICATION
MIL-STD-348A, FIG. 326.1	INTERFACE
SPECIFICATION	DESCRIPTION

CHG: ADDED NOTE 1&
NOTE 2

EC NO: URF2009-0237
2008/11/05
DRWN:CLL I
CHKD:
2008/11/11
APPR:MHUANG
2008/11/11

REV

QUALITY
SYMBOLS
▽=0
▽=0

GENERAL TOLERANCES
(UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± .---	± .---
3 PLACES	± .---	± .---
2 PLACES	± .---	± .---
1 PLACE	± .---	± .---

ANGULAR ± 2 °

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE
MM/IN

DRAWN BY	DATE
TEF	2001/05/22
CHECKED BY	DATE
SSS	2001/05/22
APPROVED BY	DATE
GMH	2001/05/22

MATERIAL NO.

SIZE C

SEE TABLE

SCALE

DESIGN UNITS
METRIC

THIRD ANGLE
PROJECTION

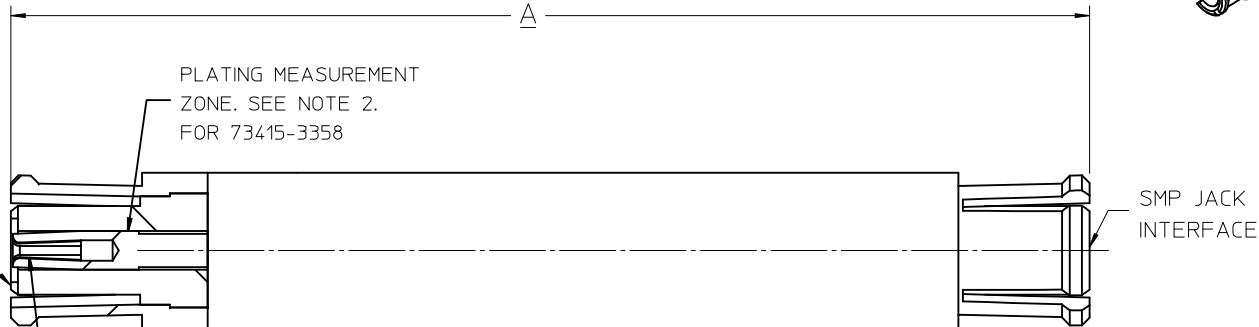
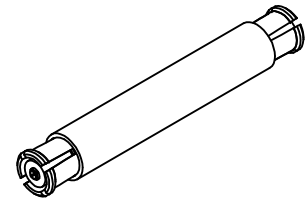
TITLE
SMP JACK TO JACK ADAPTER
50 OHMS SMP-J/J/ADP

MOLEX INCORPORATED

DOCUMENT NO.
SD-73415-335

SHEET NO.
1 OF 1

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73415-3359	.646 REF	16.40 REF
73415-3358	.677 REF	17.20 REF
73415-3357	.449 REF	11.40 REF
73415-3354	1.131 REF	28.73 REF
73415-3353	.571 REF	14.50 REF
73415-3352	.520 REF	13.21 REF
73415-3351	.799 REF	20.30 REF
73415-3350	.937 REF	23.80 REF
PART NO.	IN	MM
DIM A		